

400 WATTS - ESD PROTECTION DIODE**DESCRIPTION:**

The **ALPESDAS23T36C** is 400 Watts Peak Pulse Power per Line ($t_p=8/20\mu s$) for ESD Protection Diode are optimized for high-speed networks, data lines, ATM and power line.

FEATURES:

- 400 Watts Peak Pulse Power per Line ($t_p=8/20\mu s$)
- Solid-state silicon-avalanche technology
- Bidirectional configurations
- Low leakage current
- Low clamping voltage
- IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4A (8/20 μs)
- AEC-Q101 qualified

APPLICATIONS:

- Data lines
- Automatic Teller Machines
- Networks
- Power line

MECHANICAL CHARACTERISTICS

- SOT-23 package
- Molding compound flammability rating: UL94V-0
- Marking: Marking Code
- Packaging: Tape and Reel
- RoHS Compliant

TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)			
PARAMETER	SYMBOL	VALUES	UNITS
IEC61000-4-2 ESD Voltage – Air Mode	V _{ESD} ⁽¹⁾	±30	kV
IEC61000-4-2 ESD Voltage – Contact Mode		±30	
Peak Pulse Power	P _{PP} ⁽²⁾	400	W
Peak Pulse Current	I _{PP}	4	A
Maximum Lead Solder Temperature (10 seconds duration)	T _L	260	°C
Junction temperature	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +125	°C

Note:

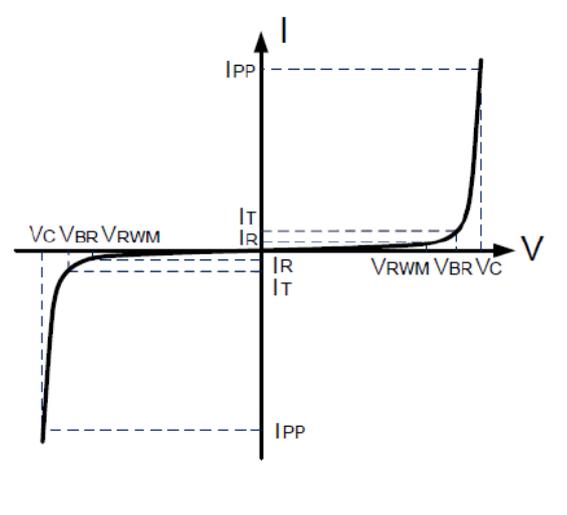
1. Device stressed with ten non-repetitive ESD pulses.
2. Non-repetitive current pulse 8/20µs exponential decay waveform according to IEC61000-4-5.
3. All ratings are measured at environmental temperature of T_A = 25°C unless otherwise noted.

ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS	SYMBOL	Min.	Typ.	Max.	UNIT
Reverse Stand-off Voltage		V _{RWM} ⁽¹⁾			36	V
Reverse Breakdown Voltage	I _T = 1mA	V _{BR}	40			V
Reverse Leakage Current	V _{RWM} = 36V	I _R			0.5	µA
Clamping Voltage @I _{PP}	I _{PP} = 4A	V _C			110	V
Junction Capacitance	V _R =0V, f=1MHz (Pin1, Pin2 to Pin3)	C _J		18	20	pF

Note:

1. Other voltages available upon request.
2. Non-repetitive current pulse 8/20µs exponential decay waveform according to IEC61000-4-5.
3. All ratings are measured at environmental temperature of T_A = 25°C unless otherwise noted.

ELECTRICAL PARAMETERS

PARAMETER	SYMBOL	
Maximum Reverse Peak Pulse Current	I_{PP}	
Clamping Voltage @ I_{PP}	V_C	
Working Peak Reverse Voltage	V_{RWM}	
Maximum Reverse Leakage Current @ V_{RWM}	I_R	
Breakdown Voltage @ I_T	V_{BR}	
Test Current	I_T	

TYPICAL DEVICE CHARACTERISTICS CURVES

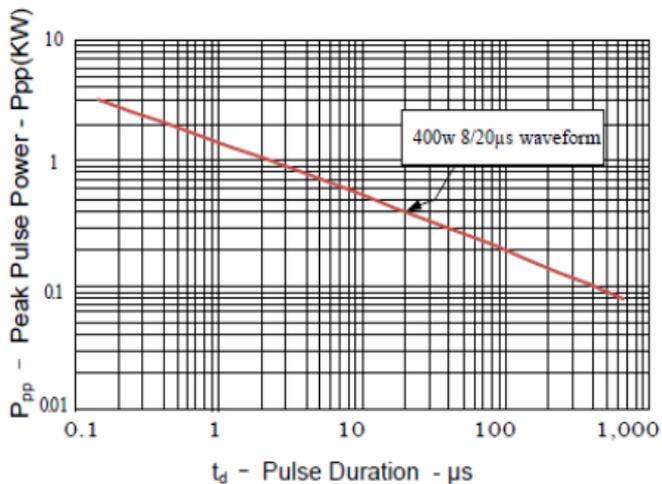


Fig1. PEAK PULSE POWER vs. PULSE TIME

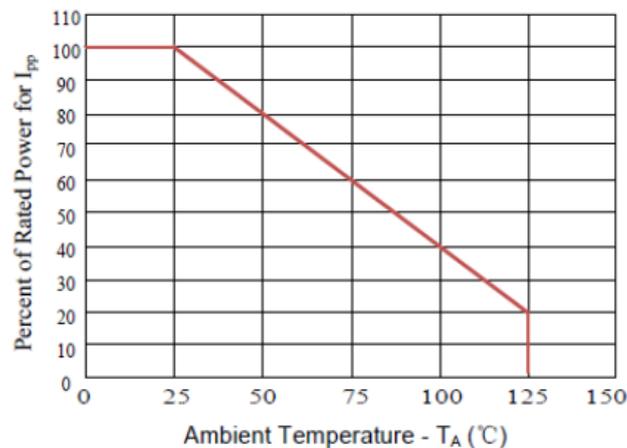


Fig2. POWER DERATING CURVE

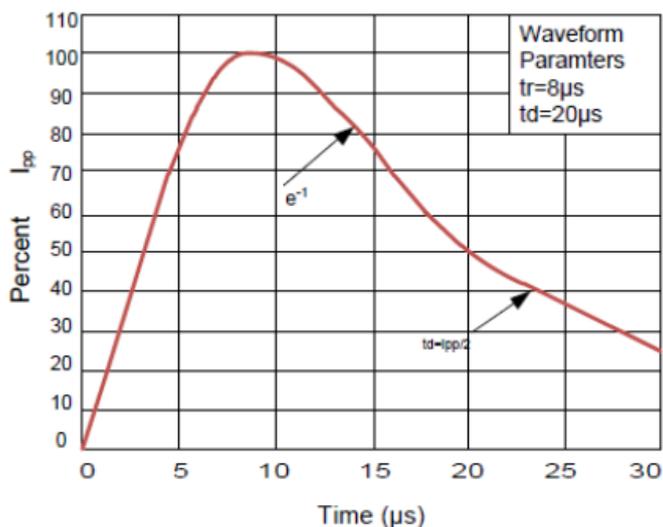


Fig3. PULSE WAVEFORM

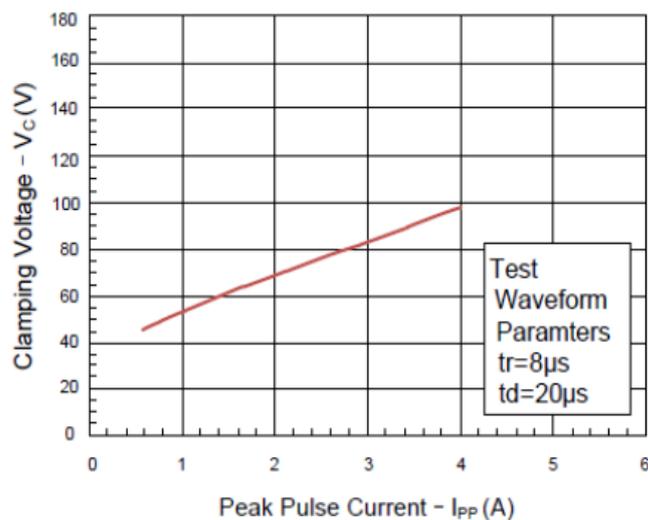
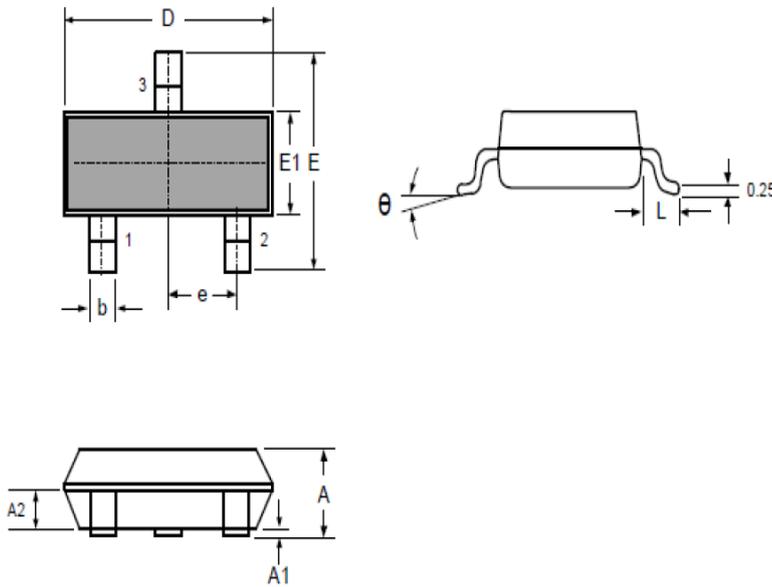


Fig4. CLAMPING VOLTAGE vs. Ipp

PACKAGE INFORMATION

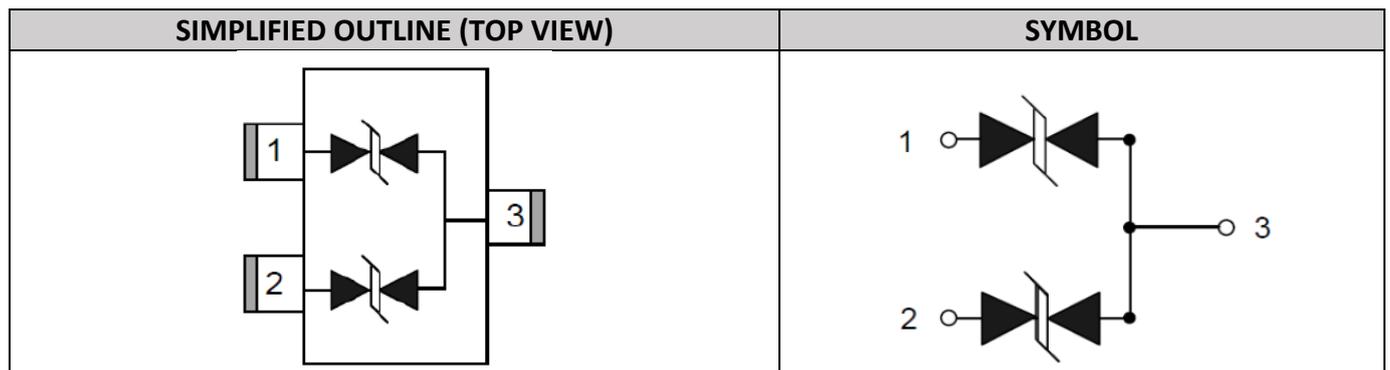
SOT-23



OUTLINE DIMENSIONS		
DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.15
A1	0.00	0.10
A2	0.90	1.05
b	0.30	0.50
D	2.80	3.00
E	2.25	2.55
E1	1.20	1.40
e	0.95 BSC	
L	0.30	0.50
θ	0°	8°

NOTES
1. Dimensions are exclusive of mold flash and metal burrs.

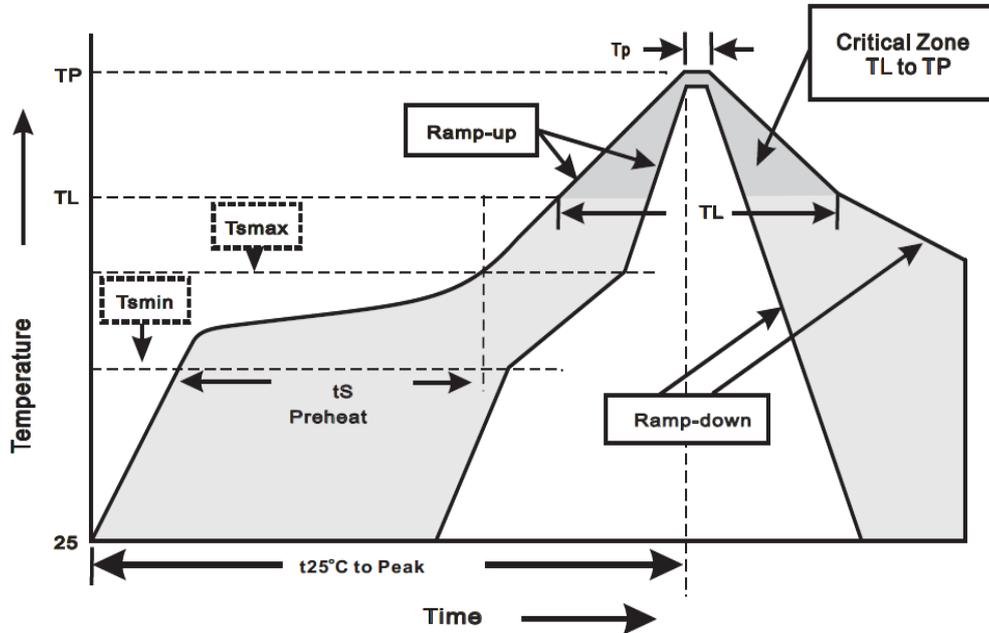
PINNING INFORMATION



SOLDERING PARAMETERS

SUGGESTED THERMAL PROFILES FOR SOLDERING PROCESSES

1. Storage environment: Temperature=5 °C~40 °C Humidity=55% ±25%
2. Reflow soldering of surface-mount devices



3. Reflow soldering

PROFILE FEATURE	SOLDERING CONDITION
Average ramp-up rate (TL to TP)	<3 °C/sec
Preheat	
- Temperature Min (T _{smin})	150 °C
- Temperature Max (T _{smax})	200 °C
- Time (min to max) (t _s)	60 ~ 120 sec
T _{smax} to TL	
- Ramp-upRate	<3 °C/sec
Time maintained above:	
- Temperature (TL)	217 °C
- Time(tL)	60 ~ 260 sec
Peak Temperature (TP)	255 °C-0/+5 °C
Time within 5 °C of actual Peak Temperature(tp)	10 ~ 30 sec
Ramp-down Rate	<6 °C/sec
Time 25 °C to Peak Temperature	<6 minutes



beyond boundaries...

ALPESDAS23T36C

SOT-23

CUSTOMER NOTE:

DISCLAIMER

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1. ALPINESEMI™ Semiconductor Devices are RoHS compliant and hence customers are requested to dispose as per the prevailing Environmental Legislation put forth in their specific country.
2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).



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